

热超声波焊线方式高精度焊线机
Highly accurate Thermo-sonic Wire Bonder

KAIJO

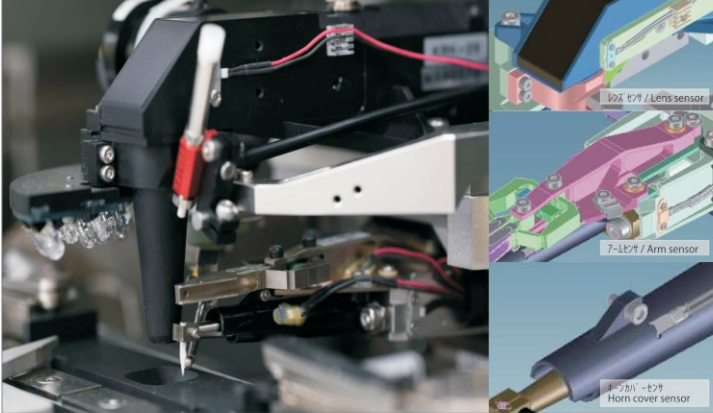
FB-e20

Bonding Accuracy

$$3\sigma \leq 2.0\mu\text{m}^*$$



Y轴位置修正感应器/摄像管
Sensor and camera tubes for position correction of Y axis



搭载扩大视野的新型镜头和高像素COMS相机，检测能力和之前一样，识别范围扩大。

Equipped with a new type lens unit with an expanded field of view and a high pixel CMOS camera. Enlarges the batch recognition area while maintaining the detection resolution.



FB-e20 的特点/FEATURES

- 更加先进的KAIJO温度修正技术，实现了焊线精度 $3\sigma \leq 2.0\mu\text{m}$
Advanced temperature compensation technology achieves bonding accuracy $3\sigma \leq 2.0\mu\text{m}^*$
- 新型镜头和高像素CMOS感应相机可以提高亮度，缩短曝光时间
Brighter and sharply defined image contributes shorter exposure time.
- 搭载USD1000型超声波发生器，提高了焊线能力。在以前的控制模式的基础上，追加了电流控制和电压控制。和程序文件组合使用，对应广泛。
Equipped with a USD-1000 ultrasonic generator that improves bondability. Current mode and Voltage mode are newly added to the conventional control mode. A wide range of support is possible in combination with the ultrasonic profile.
- 由于设备前面的形状变更，改善了操作性的同时，占地面积减少为旧款设备的87%
By changing design of the machine frame, Workability of operator is improved, and the footprint reduces 87%
- 标配SECS/GEM。也可对应KAIJO独有的管理系统KISS
SECS/GEM is accommodated as standard.
Compatible with Kaijo's own host management system KISS(Kaijo Interconnecting Service System).

主要规格

焊线能力	
焊线精度	$3\sigma \leq 2.0\mu\text{m}^*$ (不含自身编辑误差)
焊线速度	43msec [*] / 2mm
焊线范围	X: 56mm Y: 80mm
超声波	双频 (150kHz/60kHz) 振动子3种数字控制模式 (电流, 电压, 经典) 4种US文件样式可选
对应物料尺寸	
线径和线的种类	金线, 铜线, 银线 $\phi 15 \sim 30\mu\text{m}$ ($\phi 30 \sim 75\mu\text{m}$ 可选对应)
支架尺寸	宽 : 20 ~ 90mm 长 : 90 ~ 300mm 厚 : 0.1 ~ 0.5mm
料盒尺寸	宽 : 30 ~ 110mm 长 : 90 ~ 305mm 高 : 100 ~ 175mm 料盒存放数量 : 2 ~ 3 料盒
工程管理功能	
生产管理信息	线消耗, 瓷嘴消耗, 生产数, 运行/停止时间, 报警等
品质管理信息	加热温度, 空气流量
自我诊断信息	打火/US发电机, XY平台, Z轴支点弹
跟踪性	打火时电流, 电压, US电流, 阻抗, 频数, 不良数, 加重控制, 线弧动作追踪, 发生报警时波形记录
外部通信功能	
	SECS/GEM, KISS (Kaijo Interconnecting Service System)
用途	
电源	单相 AC200V \pm 5%, 50Hz/60Hz, 8A (选配、AC100V, 210V, 220V, 230V, 240V 可变更) 最大消费电力: 约 1.5kW
空气	压力 : 0.3 ~ 0.970MPa (3 ~ 9.9Kgf/cm ²) 消费量: 40Liters/min 以下
真空	压力 : -53.32MPa 以下 (400mm/Hg 以上)
諸元	
尺寸	宽 : 940mm 长 : 1,025mm 高 : 1,725mm (包含信号灯H1960mm)
重量	重量 : 约 560kg

SPECIFICATIONS

Bondability	
Bonding accuracy	$3\sigma \leq 2.0\mu\text{m}^*$ (Excluding errors caused by Self-teaching)
Bonding speed	43msec [*] / 2mm wire length
Bonding area	X: 56mm Y: 80mm
Ultrasonic	Dual frequency transducer (150 kHz / 60kHz) Selectable combinations: 3 digital control modes \times 4 ultrasonic profiles
Applicable work size	
Wire	Material: Au, Cu, Ag Diameter: $\phi 15 \sim 30\mu\text{m}$ ($\phi 30 \sim 75\mu\text{m}$ is available as an option)
Package Frame size	Width: 20 ~ 90mm Length: 90 ~ 300mm Thickness: 0.1 ~ 0.5mm
Magazine size	Width: 30 ~ 110mm Length: 90 ~ 305mm Height: 100 ~ 175mm Stockable magazine: 2 ~ 3 magazines
Process management	
Production management	Wire consumption, Tool touch counter, Output, Running/Resting time, Alarm indication, etc.
Quality-control	Heater temperature, Airflow meter, etc.
Self-diagnosis	Spark / Ultrasonic generator, XY-stage, Z axis fulcrum, etc.
Traceability	Spark Current/Voltage, Ultrasonic current, Impedance, Frequency, Ball smash control, Bond force, Loop track-following control, Waveform in each error, etc.
External interface	
	SECS/GEM, KISS (Kaijo Interconnecting Service System)
Utility	
Power	Single phase AC200V \pm 5%, 50Hz/60Hz, 8A (AC100V, 210V, 220V, 230V, 240V option) Maximum power consumption: approximately 1.5kW
Dry air	Pressure: 0.3 ~ 0.970MPa (3 ~ 9.9Kgf/cm ²) Consumption: 40Liters/min or less
Vacuum	Pressure: -53.32MPa or less (400mm/Hg or more)
Dimensions	
Width	940mm
Depth	1,025mm
Height	1,725mm (to top of signal lamp: 1,960mm)
Weight	approximately 560kg

⚠ 注意事项: 为了安全使用商品, 使用前请仔细阅读操作说明书。

● 目录上的注意...目录上所刊载商品的规格以及外观如有所改良恕不另行通知, 请悉知。

⚠ CAUTION FOR SAFE: Please read surely INSTRUCTION MANUAL before operate.

● Specification is subject to change without prior notice for improvement.

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